NOTES: 1. Conector materials:
CONTACTS/SHIELD. COPPER AL V-
SHIELD PLATING: NICKEL

- Chative plating in contact area
ale clear polycarbonate
Logo, part number and date cooe located approx. in this area

3. Recommended min PCB thickness .062" (1.50mm)
$\triangle$ datum and basic dimension established by customer
Sfor hole size and platings, see sheet 3
© Recommended smt led manufacturers and pi
EVERLIGHT P/N: $18-225 /$ R6G6C-A0I/3T OR
PARaLIGHT P/N: L-Cl 85 KFKGWT
refer to proouct specification pro36-01



RJP5-10-0010
 [0.13um] Au OVER 30 MICRO-INCHES $[0.76 \mathrm{um}]$ PdNi
contact plating
PART NUMBER

## third angle projection CONNECTO

DO NOT SCALE draw ing is sub Ject t $-$

JPOINT FIVE, JACK, POE+, HORIZONTAL,
RoHS

| RJ polnt five is |
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sed here by permission



RECOMMENDED HOLE DIMENSIONS
FOR SIGNAL CONTACTS

drilled Hole dillameter
RECOMMENDED HOLE DIMENSIONS

| SUGGESTED HOLE CONSTRUCTION |  |  |
| :---: | :---: | :---: |
| thickness (mil inch) | thickness (mm) | plating |
| 0.1575-0.3937 | 0.004-0.010 | Hot alr solder leveling (hasl) tin-Lead ( $\mathrm{S}_{\text {n Pb }}$ ) |
| 0.0197-0.0394 | 0.0005-0.001 | IMMERSION TIN (Sn) |
| 0.0079-0.0197 | 0.0002-0.0005 | ORGANIC SOLDERABILIty Preservative (OSP) |
| 0.0039-0.0197 Au, 0.1575-0.2992 Ni | $0.0001-0.0005 \mathrm{Au}, 0.004-0.0076 \mathrm{Ni}$ | IMMERSION GOLD (Au) OVER NICKEL (Ni) (ENIG) |
| 0.3937-0.9843 | 0.010-0.025 | TIN LEAD PLATING ( $\mathrm{Sn} \mathrm{Pb}_{\text {P }}$ |
| 0.0039-0.0059 | 0.0001-0.00015 | IMMERSION SILVER ( Ag ) |

1118 Susquehanna Trail South Glen Rock, PA 17327-9199

DO NOT SCALE DRAWING drawing is sub Ject to

TITLE: RJ
T POINT FIVE, JACK, POE HORIDONTAL,
RoHS DIMENSIONS: INCHES [WETRIC]


ANGLES ARE $\pm 1$
SHET No.






